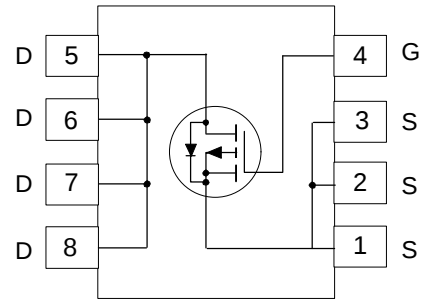


General Description

These devices are well suited for notebook computer applications: load switching and power management, battery charging circuits, and DC/DC conversion.

Features

- $V_{DS} (V) = -30V$
- $I_D = -11 A (V_{GS} = -10V)$
- $R_{DS(ON)} < 14m\Omega (V_{GS}=10V)$
- $R_{DS(ON)} < 20 m\Omega (V_{GS}=4.5V)$



SOP-8

Absolute Maximum Ratings

$T_A = 25^\circ C$ unless otherwise noted

Symbol	Parameter	FDS6675	Units
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current - Continuous (Note 1a) - Pulsed	-11	A
		-50	
P_D	Power Dissipation for Single Operation (Note 1a) (Note 1b) (Note 1c)	2.5	W
		1.2	
		1	
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to 150	$^\circ C$

THERMAL CHARACTERISTICS

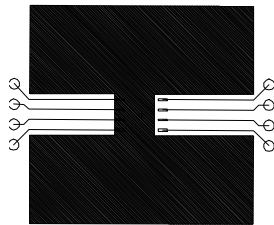
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1a)	50	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case (Note 1)	25	$^\circ C/W$

Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

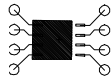
Symbol	Parameter	Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = -250 μA	-30			V
ΔBV _{DSS} /ΔT _J	Breakdown Voltage Temp. Coefficient	I _D = -250 μA, Referenced to 25 °C		-22		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -24 V, V _{GS} = 0 V			-1	μA
		T _J = 55°C			-10	μA
I _{GSSF}	Gate - Body Leakage, Forward	V _{GS} = 20 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate - Body Leakage, Reverse	V _{GS} = -20 V, V _{DS} = 0 V			-100	nA
ON CHARACTERISTICS (Note 2)						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = -250 μA	-1	-1.5	-2	V
ΔV _{GS(th)} /ΔT _J	Gate Threshold Voltage Temp. Coefficient	I _D = 250 μA, Referenced to 25 °C		4.3		mV/°C
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} = -10 V, I _D = -11 A		11	14	mΩ
		V _{GS} = -4.5 V, I _D = -9 A		15	20	
I _{D(ON)}	On-State Drain Current	V _{GS} = -10 V, V _{DS} = -5 V	-50			A
g _{FS}	Forward Transconductance	V _{DS} = -10 V, I _D = -11 A		32		S
DYNAMIC CHARACTERISTICS						
C _{iss}	Input Capacitance	V _{DS} = -15 V, V _{GS} = 0 V, f = 1.0 MHz		3000		pF
C _{oss}	Output Capacitance			870		pF
C _{rss}	Reverse Transfer Capacitance			360		pF
SWITCHING CHARACTERISTICS (Note 2)						
t _{D(on)}	Turn - On Delay Time	V _{DS} = -15 V, I _D = -1 A V _{GEN} = -10 V, R _{GEN} = 6 Ω		12	22	ns
t _r	Turn - On Rise Time			16	27	ns
t _{D(off)}	Turn - Off Delay Time			50	80	ns
t _f	Turn - Off Fall Time			100	140	ns
Q _g	Total Gate Charge	V _{DS} = -15 V, I _D = -11 A, V _{GS} = -5 V		30	42	nC
Q _{gs}	Gate-Source Charge			9		nC
Q _{gd}	Gate-Drain Charge			11		nC
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
I _S	Maximum Continuous Drain-Source Diode Forward Current				-2.1	A
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = -2.1 A (Note 2)		-0.72	-1.2	V

Notes:

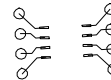
- R_{JA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{JA} is guaranteed by design while R_{JC} is determined by the user's board design.



a. 50°C/W on a 0.5 in^2 pad of 2oz copper.



b. 105°C/W on a 0.02 in^2 pad of 2oz copper.



c. 125°C/W on a 0.003 in^2 pad of 2oz copper.

Scale 1 : 1 on letter size paper

- Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2.0\%$.

Typical Electrical Characteristics

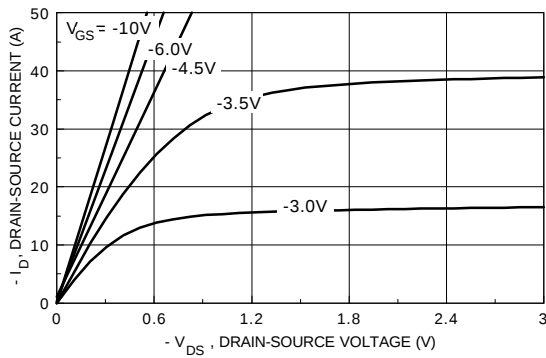


Figure 1. On-Region Characteristics.

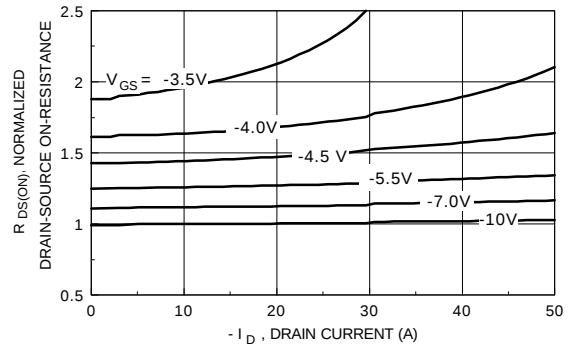


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

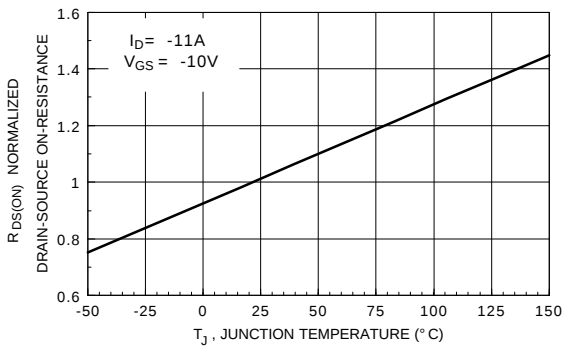


Figure 3. On-Resistance Variation with Temperature.

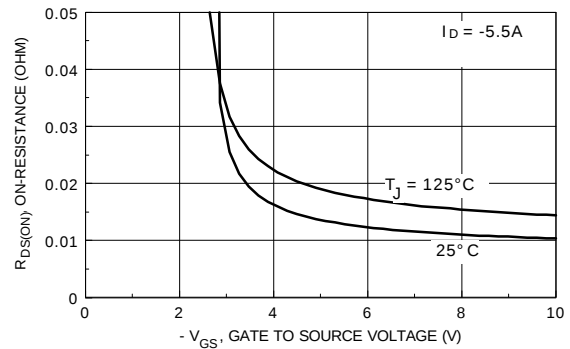


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

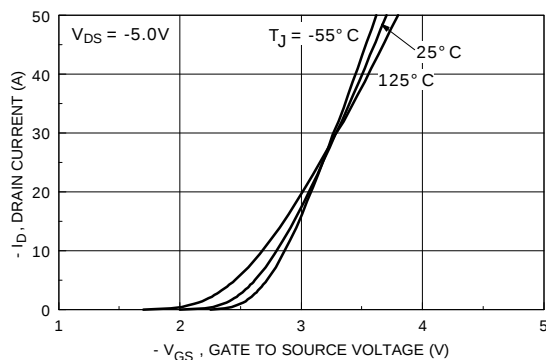


Figure 5. Transfer Characteristics.

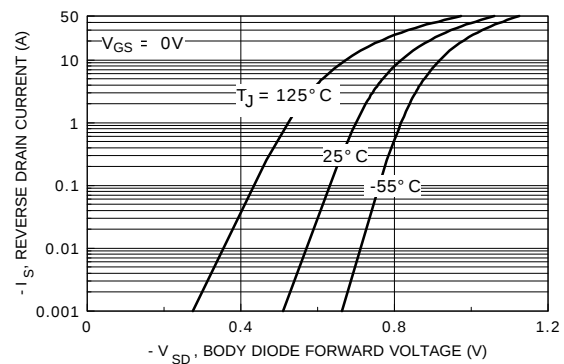


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Electrical Characteristics (continued)

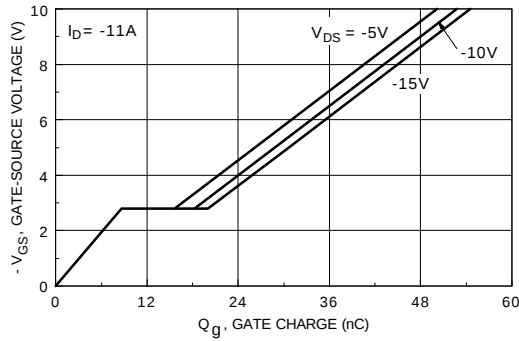


Figure 7. Gate Charge Characteristics.

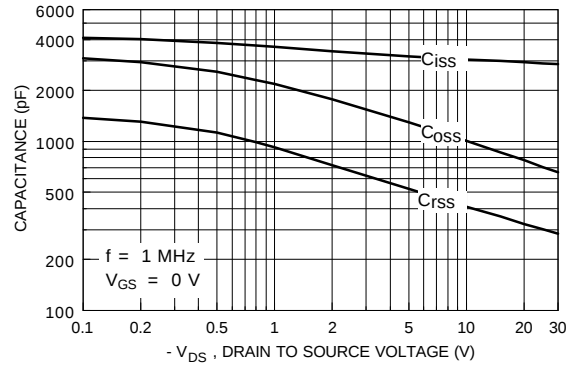


Figure 8. Capacitance Characteristics.

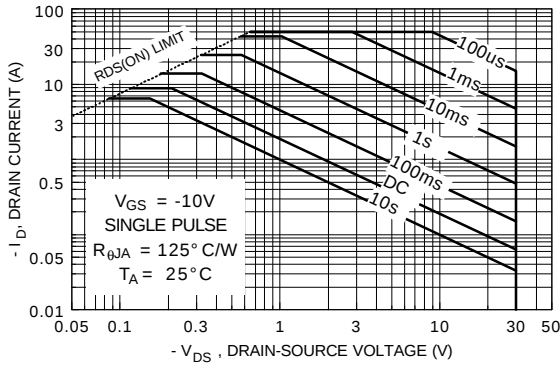


Figure 9. Maximum Safe Operating Area.

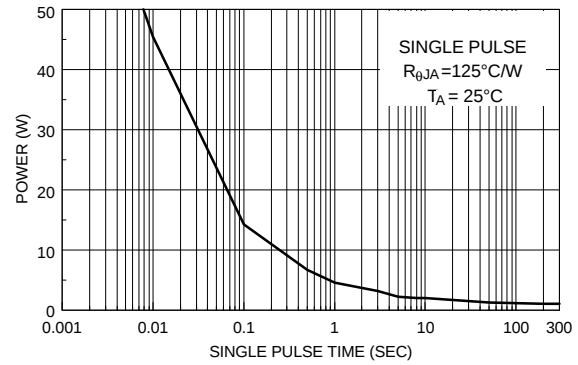


Figure 10. Single Pulse Maximum Power Dissipation.

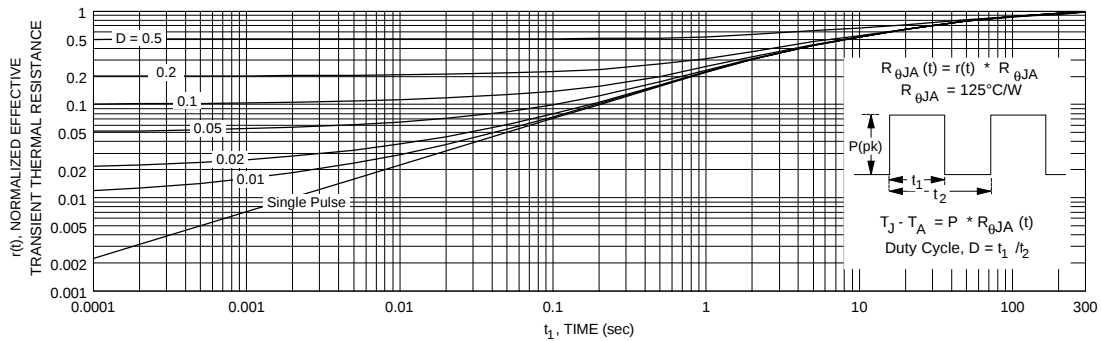
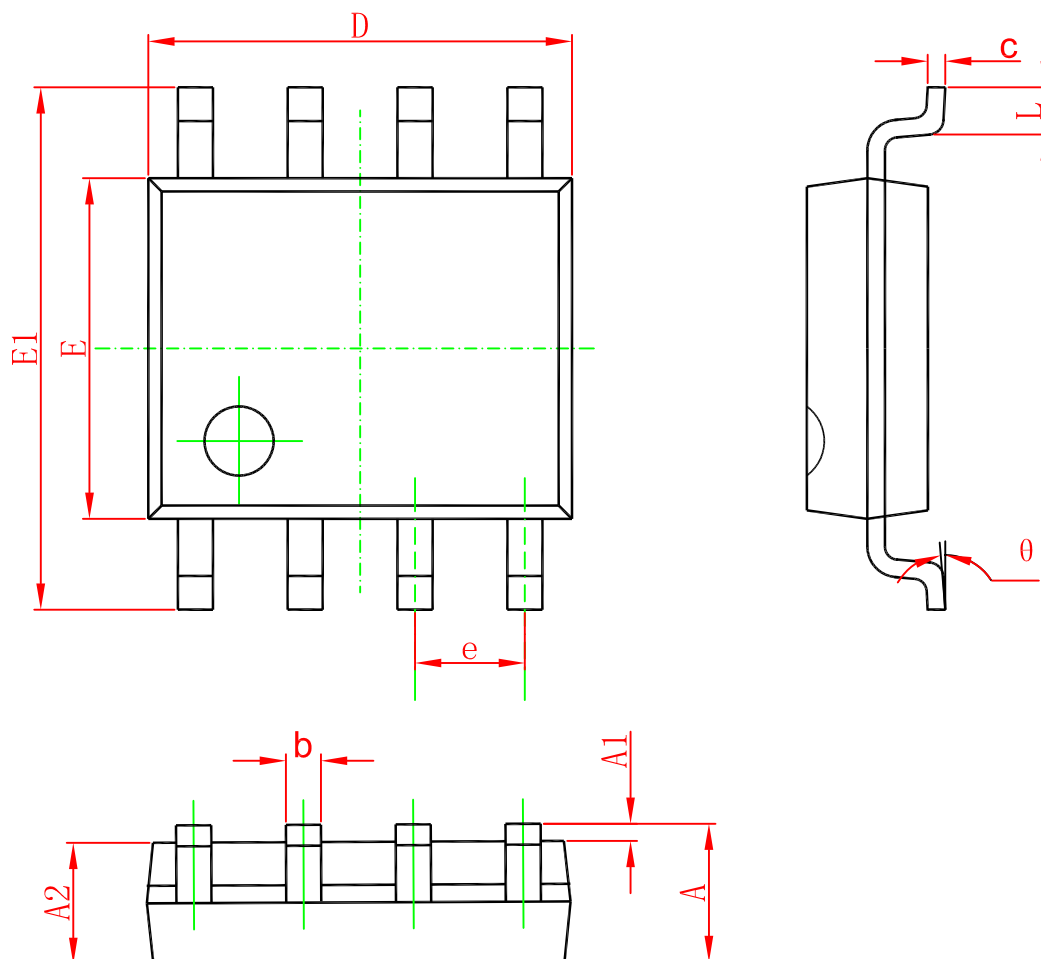


Figure 11. Transient Thermal Response Curve.

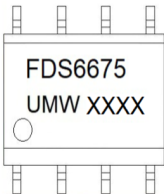
Thermal characterization performed using the conditions described in Note 1c.
Transient thermal response will change depending on the circuit board design.

Package Mechanical Data SOP-8



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

Marking



Ordering information

Order code	Package	Baseqty	Deliverymode
UMW FDS6675	SOP-8	3000	Tape and reel